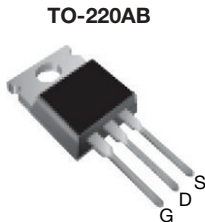


## Power MOSFET

| PRODUCT SUMMARY           |                             |
|---------------------------|-----------------------------|
| $V_{DS}$ (V)              | 200                         |
| $R_{DS(on)}$ ( $\Omega$ ) | $V_{GS} = 10\text{ V}$ 0.18 |
| $Q_g$ (Max.) (nC)         | 70                          |
| $Q_{gs}$ (nC)             | 13                          |
| $Q_{gd}$ (nC)             | 39                          |
| Configuration             | Single                      |



### FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- Fast switching
- Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



RoHS\*  
Available

### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

### DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

| ORDERING INFORMATION |            |
|----------------------|------------|
| Package              | TO-220AB   |
| Lead (Pb)-free       | IRF640PbF  |
|                      | SiHF640-E3 |
| SnPb                 | IRF640     |
|                      | SiHF640    |

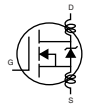

| ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted) |                                  |                |                                   |                     |          |
|---|----------------------------------|----------------|-----------------------------------|---------------------|----------|
| PARAMETER   |                                  | SYMBOL         | LIMIT                             | UNIT                |          |
| Drain-Source Voltage  |                                  | $V_{DS}$       | 200                               | V                   |          |
| Gate-Source Voltage   |                                  | $V_{GS}$       | $\pm 20$                          |                     |          |
| Continuous Drain Current  | $V_{GS}$ at 10 V                 | $I_D$          | $T_C = 25\text{ }^\circ\text{C}$  | 18                  | A        |
|   |                                  |                | $T_C = 100\text{ }^\circ\text{C}$ | 11                  |          |
| Pulsed Drain Current <sup>a</sup>   |                                  | $I_{DM}$       | 72                                |                     |          |
| Linear Derating Factor  |                                  |                | 1.0                               | W/ $^\circ\text{C}$ |          |
| Single Pulse Avalanche Energy <sup>b</sup>  |                                  | $E_{AS}$       | 580                               | mJ                  |          |
| Repetitive Avalanche Current <sup>a</sup>   |                                  | $I_{AR}$       | 18                                | A                   |          |
| Repetitive Avalanche Energy <sup>a</sup>  |                                  | $E_{AR}$       | 13                                | mJ                  |          |
| Maximum Power Dissipation   | $T_C = 25\text{ }^\circ\text{C}$ | $P_D$          | 125                               | W                   |          |
| Peak Diode Recovery dV/dt <sup>c</sup>  |                                  | dV/dt          | 5.0                               | V/ns                |          |
| Operating Junction and Storage Temperature Range                                      |                                  | $T_J, T_{stg}$ | -55 to +150                       | $^\circ\text{C}$    |          |
| Soldering Recommendations (Peak temperature) <sup>d</sup>                             | for 10 s                         |                | 300                               |                     |          |
| Mounting Torque   | 6-32 or M3 screw                 |                | 10                                |                     | lbf · in |
|   |                                  |                | 1.1                               | N · m               |          |

### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 50\text{ V}$ , starting  $T_J = 25\text{ }^\circ\text{C}$ ,  $L = 2.7\text{ mH}$ ,  $R_g = 25\text{ }^\circ\Omega$ ,  $I_{AS} = 18\text{ A}$  (see fig. 12).
- $I_{SD} \leq 18\text{ A}$ ,  $dI/dt \leq 150\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150\text{ }^\circ\text{C}$ .
- 1.6 mm from case.



| THERMAL RESISTANCE RATINGS          |            |      |      |      |
|-------------------------------------|------------|------|------|------|
| PARAMETER                           | SYMBOL     | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient         | $R_{thJA}$ | -    | 62   | °C/W |
| Case-to-Sink, Flat, Greased Surface | $R_{thCS}$ | 0.50 | -    |      |
| Maximum Junction-to-Case (Drain)    | $R_{thJC}$ | -    | 1.0  |      |

| SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted) |                     |   |      |      |           |               |
|---|---------------------|---|------|------|-----------|---------------|
| PARAMETER   | SYMBOL              | TEST CONDITIONS   | MIN. | TYP. | MAX.      | UNIT          |
| <b>Static</b>   |                     |   |      |      |           |               |
| Drain-Source Breakdown Voltage  | $V_{DS}$            | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$   | 200  | -    | -         | V             |
| $V_{DS}$ Temperature Coefficient  | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^\circ\text{C}$ , $I_D = 1\text{ mA}$   | -    | 0.29 | -         | V/°C          |
| Gate-Source Threshold Voltage   | $V_{GS(th)}$        | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$   | 2.0  | -    | 4.0       | V             |
| Gate-Source Leakage   | $I_{GSS}$           | $V_{GS} = \pm 20\text{ V}$  | -    | -    | $\pm 100$ | nA            |
| Zero Gate Voltage Drain Current   | $I_{DSS}$           | $V_{DS} = 200\text{ V}, V_{GS} = 0\text{ V}$  | -    | -    | 25        | $\mu\text{A}$ |
|   |                     | $V_{DS} = 160\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$   | -    | -    | 250       |               |
| Drain-Source On-State Resistance  | $R_{DS(on)}$        | $V_{GS} = 10\text{ V}, I_D = 11\text{ A}^b$   | -    | -    | 0.18      | $\Omega$      |
| Forward Transconductance  | $g_{fs}$            | $V_{DS} = 50\text{ V}, I_D = 11\text{ A}^b$   | 6.7  | -    | -         | S             |
| <b>Dynamic</b>  |                     |   |      |      |           |               |
| Input Capacitance   | $C_{iss}$           | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$ , see fig. 5  | -    | 1300 | -         | pF            |
| Output Capacitance  | $C_{oss}$           |   | -    | 430  | -         |               |
| Reverse Transfer Capacitance  | $C_{rss}$           |   | -    | 130  | -         |               |
| Total Gate Charge   | $Q_g$               | $V_{GS} = 10\text{ V}, I_D = 18\text{ A}, V_{DS} = 160\text{ V}$ , see fig. 6 and 13 <sup>b</sup>   | -    | -    | 70        | nC            |
| Gate-Source Charge  | $Q_{gs}$            |   | -    | -    | 13        |               |
| Gate-Drain Charge   | $Q_{gd}$            |   | -    | -    | 39        |               |
| Turn-On Delay Time  | $t_{d(on)}$         | $V_{DD} = 100\text{ V}, I_D = 18\text{ A}, R_g = 9.1\text{ }\Omega, R_D = 5.4\text{ }\Omega$ , see fig. 10 <sup>b</sup>                                 | -    | 14   | -         | ns            |
| Rise Time   | $t_r$               |   | -    | 51   | -         |               |
| Turn-Off Delay Time   | $t_{d(off)}$        |   | -    | 45   | -         |               |
| Fall Time   | $t_f$               |   | -    | 36   | -         |               |
| Internal Drain Inductance   | $L_D$               | Between lead, 6 mm (0.25") from package and center of die contact  | -    | 4.5  | -         | nH            |
| Internal Source Inductance  | $L_S$               |   | -    | 7.5  | -         |               |
| Gate Input Resistance   | $R_g$               | $f = 1\text{ MHz}$ , open drain   | 0.5  | -    | 3.6       | $\Omega$      |
| <b>Drain-Source Body Diode Characteristics</b>                              |                     |   |      |      |           |               |
| Continuous Source-Drain Diode Current                                       | $I_S$               | MOSFET symbol showing the integral reverse p - n junction diode    | -    | -    | 18        | A             |
| Pulsed Diode Forward Current <sup>a</sup>                                   | $I_{SM}$            |   | -    | -    | 72        |               |
| Body Diode Voltage  | $V_{SD}$            | $T_J = 25\text{ }^\circ\text{C}, I_S = 18\text{ A}, V_{GS} = 0\text{ V}^b$  | -    | -    | 2.0       | V             |
| Body Diode Reverse Recovery Time  | $t_{rr}$            | $T_J = 25\text{ }^\circ\text{C}, I_F = 18\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$   | -    | 300  | 610       | ns            |
| Body Diode Reverse Recovery Charge  | $Q_{rr}$            |   | -    | 3.4  | 7.1       | $\mu\text{C}$ |
| Forward Turn-On Time  | $t_{on}$            | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )   |      |      |           |               |

**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\text{ }\%$ .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

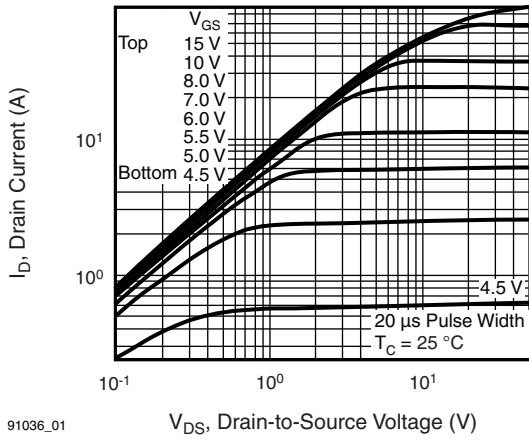


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C



Fig. 4 - Normalized On-Resistance vs. Temperature

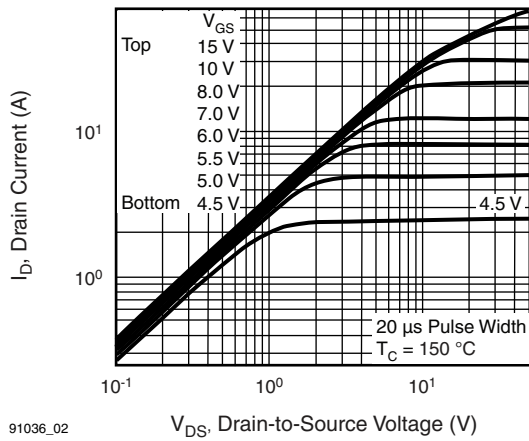


Fig. 2 - Typical Output Characteristics, T<sub>C</sub> = 150 °C

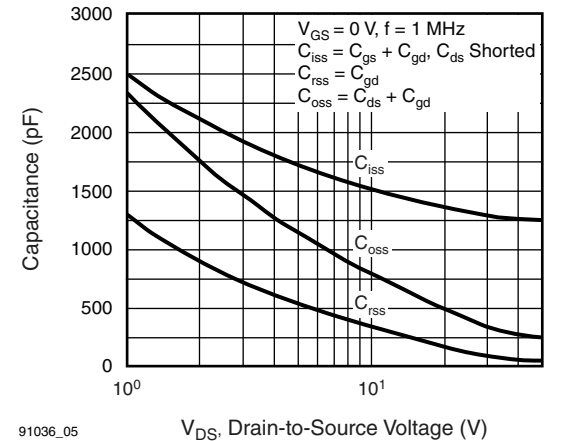


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

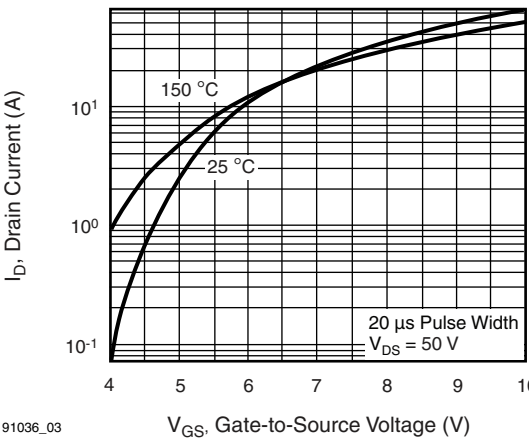


Fig. 3 - Typical Transfer Characteristics

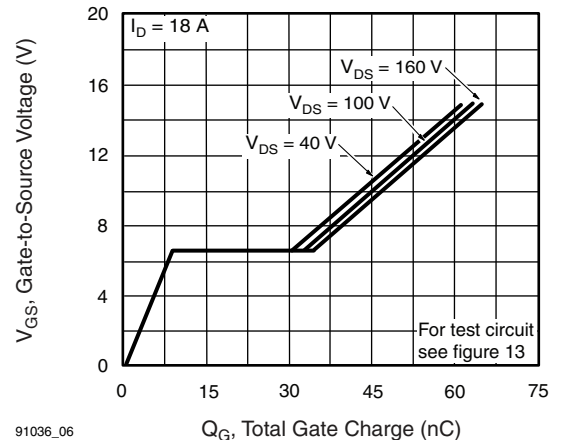
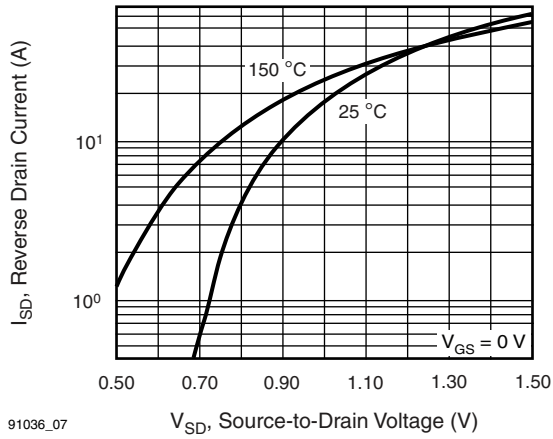
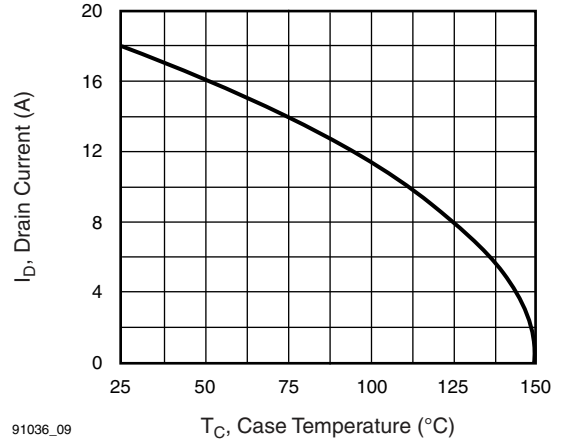


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



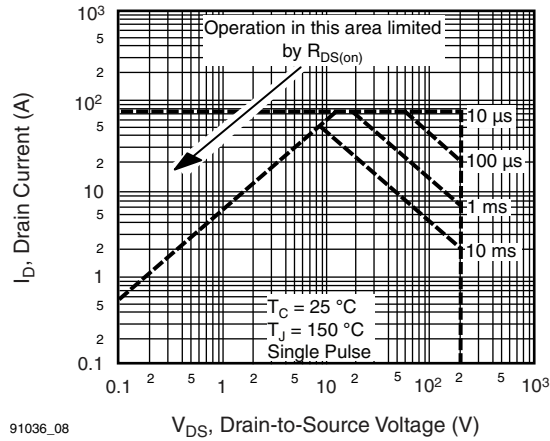
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Fig. 7 - Typical Source-Drain Diode Forward Voltage



91036\_09

Fig. 9 - Maximum Drain Current vs. Case Temperature



91036\_08

Fig. 8 - Maximum Safe Operating Area

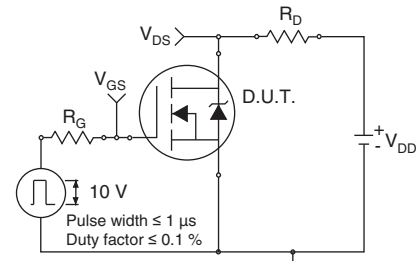


Fig. 10a - Switching Time Test Circuit

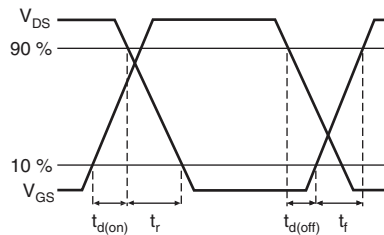
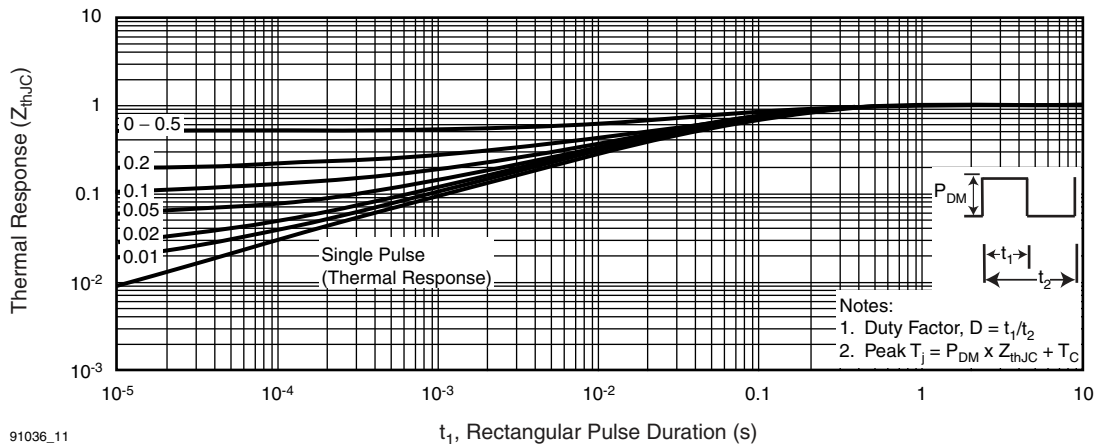


Fig. 10b - Switching Time Waveforms



91036\_11

Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



Fig. 12a - Unclamped Inductive Test Circuit

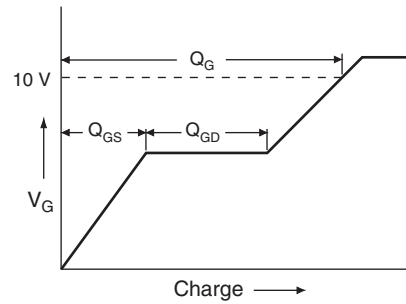


Fig. 13a - Basic Gate Charge Waveform

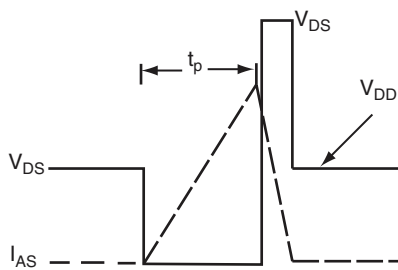


Fig. 12b - Unclamped Inductive Waveforms

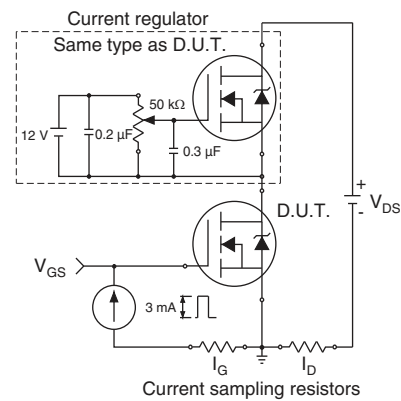


Fig. 13b - Gate Charge Test Circuit

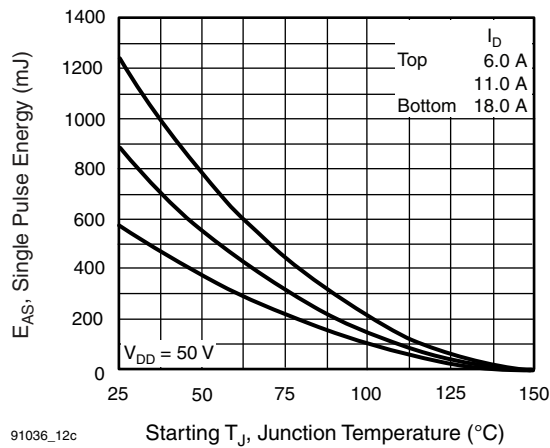
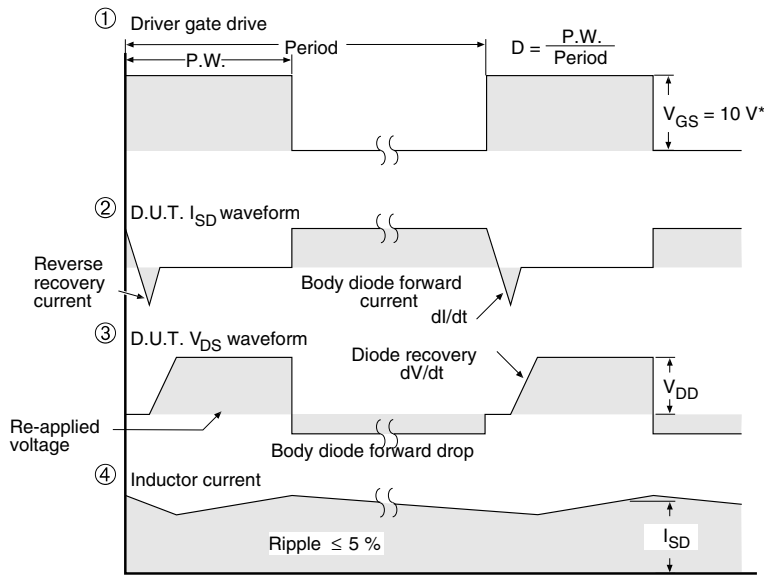
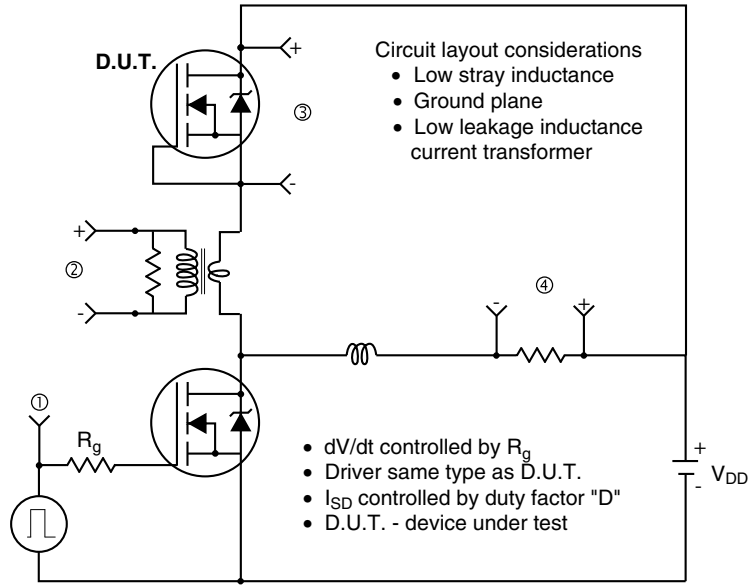


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

**Peak Diode Recovery dV/dt Test Circuit**



\*  $V_{GS} = 5 V$  for logic level devices

**Fig. 14 - For N-Channel**

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